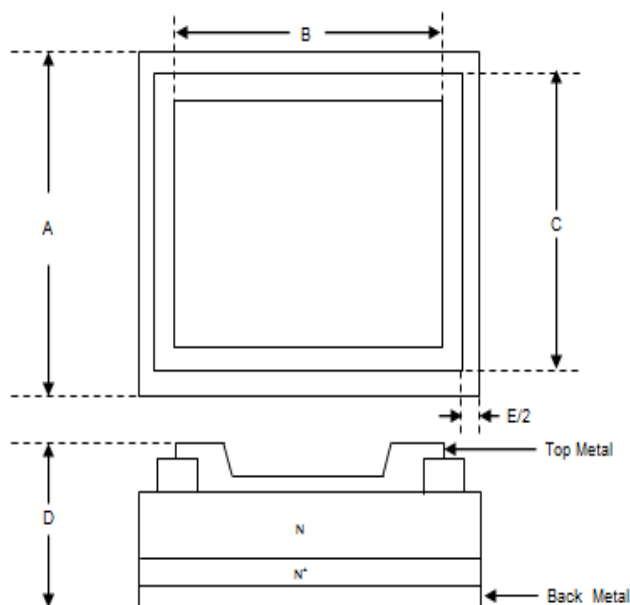


Trench Schottky Barrier Diode Wafer (TSBD)

Preliminary



Item	Dimensions	
	um	mil
Die Size (A)	1834	72
Top Metal Pad Size (B)	1660	65.3
Passivation Seal (C)	1764	69.4
Wafer Thickness (D)	260	10.2
Scribe Line Width (E)	70	2.76
Other Informations		
Wafer Size	6"	
Gross Die	4760	
Top Metal	Ag	
Back Metal	Ag	

Electrical Characteristics @TA=25°C

Item	Symbol	Spec. Limit	Die Sort	Unit
Maximum Repetitive Peak Reverse Voltage @0.1mA	V_{RRM}	100	106	V
Maximum Average Forward Rectified Current	I_O	10	-	A
Forward Voltage Drop, @ $I_F=3A$ @ $I_F=5A$ @ $I_F=10A$	V_F	- 0.62 0.80	0.54 -	V
Maximum Reverse Current at Rated V_{RRM}	I_R	30	15	μA
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	120	-	A
Operating Temperature Range	T_J	-50 to +150	-	°C
Storage Temperature Range	T_{STG}	-50 to +150	-	°C